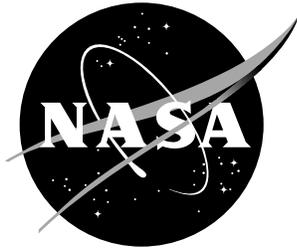


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Assembly and Integration of Superconductive Measurement Circuits for a Spaceflight Experiment

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September 1998

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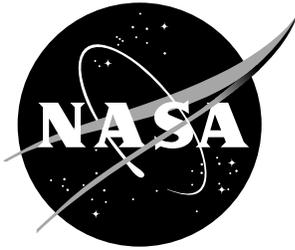
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ABSTRACT

Hybrid microelectronics containing both conventional electronic components and high-temperature superconductive films have been designed, fabricated, and tested. The devices operate from room temperature to 75K and perform d.c. four-probe resistance measurements on six superconductive specimens resident on each circuit. Four of these hybrid circuits were incorporated into the Materials In Devices As Superconductors (MIDAS) spaceflight experiment and evaluated over a 90-day period on the Mir space station. Prior to launch, comprehensive testing of the flight circuits was performed to determine the effects of thermal cycling, vibration loads, and long-term operation on circuit performance. This report describes the fabrication and assembly procedures used to produce the hybrid circuits, the techniques used to integrate the circuits into the MIDAS hardware system, and the results of pre-flight evaluations which verified circuit functionality.

INTRODUCTION

High-temperature superconductors have been proposed for use in several spacecraft systems due to their unique electrical, magnetic, and thermal properties (refs. 1-3). In each instance, the replacement of existing materials with high-temperature superconductors would either significantly increase the performance capability of the spacecraft instrument or substantially reduce the payload size and weight, thereby reducing launch costs. Furthermore, several spacecraft already employ cryogenic refrigeration systems, providing an operational environment well-suited for the use of superconductive devices.

Thick films of high-temperature superconductive materials have been fabricated using conventional manufacturing processes such as screen printing. These films have been deposited onto polycrystalline ceramic substrates such as Al_2O_3 and ZrO_2 and have been found to exhibit critical current density, J_c , values up to 100 A/cm^2 (refs. 4-8). Although the J_c properties of these films are lower than those of preferentially-oriented thin films of the same materials, the thick films do exhibit sufficient performance characteristics for many aerospace applications (refs. 1 and 3).

Thin film superconductors have been produced using several vacuum deposition processes including sputtering (ref. 9), laser ablation (ref. 10), and vapor deposition (ref. 11). These materials are typically deposited onto single crystal substrates such as (100) SrTiO_3 and (100) LaAlO_3 ,

which have lattice constants similar to that of $\text{YBa}_2\text{Cu}_3\text{O}_{7-x}$. The similarity of the lattice constants allows the growth of superconductive films with the c-axis perpendicular to the substrate. Because of the preferred orientation of the films, these materials have been reported to exhibit J_c values in excess of 10^6 A/cm^2 (ref. 12).

To demonstrate the feasibility of using high-temperature superconductors in spacecraft systems, films of the $\text{YBa}_2\text{Cu}_3\text{O}_{7-x}$ material were integrated with conventional circuitry to produce active microelectronics packages. These hybrid circuits were designed to operate at cryogenic temperatures and enable the performance properties of six superconductive films incorporated into each circuit to be determined. Although specifically designed to perform electrical measurements, the processes and procedures used to fabricate and assemble the circuits could be applied to produce devices for many spacecraft applications.

To alleviate concerns regarding the survivability of superconductive devices under launch vibrations and their long-term performance in a microgravity environment, four hybrid circuits were integrated into the Materials In Devices As Superconductors (MIDAS) spaceflight experiment and tested on orbit. The MIDAS experiment was launched on Space Transportation System mission 79 (STS-79) in September of 1996, transferred to the Priroda module of the Mir space station, and operated for 90 days prior to its return to Earth on STS-81 in January of 1997. This report describes the fabrication and assembly procedures used to produce the hybrid circuits for the MIDAS experiment, the techniques used to integrate the circuits with the MIDAS hardware system, and the results of pre-flight evaluations of circuit performance.

EXPERIMENTAL PROCEDURE

Hybrid Circuit Assembly

The $\text{YBa}_2\text{Cu}_3\text{O}_{7-x}$ superconductive material used for thick film deposition was synthesized by the solid-state reaction of Y_2O_3 , BaCO_3 , and CuO . After synthesis, the powder was ball-milled in acetone to produce an average particle size of $12 \mu\text{m}$. A thick-film printing paste was prepared by blending the $\text{YBa}_2\text{Cu}_3\text{O}_{7-x}$ powder with an organic carrier vehicle using a solids content of 75 per cent by weight. The paste was then screen printed onto polycrystalline yttria-stabilized zirconia (YSZ) substrates using a 200-mesh screen patterned by photolithography. The printed films were dried at 200°C and then sintered for 60 minutes at 950°C in air. During cooling, an oxygen atmosphere was introduced into the furnace, and the films were annealed at 600°C for six hours to allow the oxygen content of the films to equilibrate. The details regarding the

sintering of the $\text{YBa}_2\text{Cu}_3\text{O}_{7-x}$ superconductive films have been reported elsewhere (ref. 7).

For each hybrid circuit, six superconductive films of dimensions 1.02 x 0.10 cm were deposited onto a 2.54- x 2.54- x 0.10-cm YSZ substrate and sintered as previously described. Gold conductive paths for connection to the measurement circuitry and four silver electrical contacts per superconductive film were then deposited using electron-beam evaporation. A photograph showing a typical YSZ substrate containing six superconductive films and a substrate with both superconductive films and gold conductive paths is provided in Figure 1.

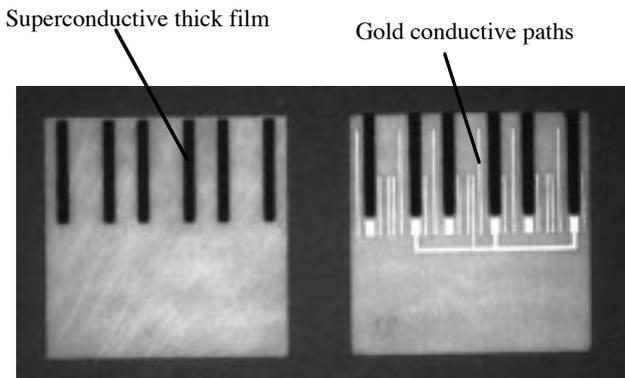


Figure 1. Photograph showing a typical YSZ substrate containing six superconductive films (left) and a substrate with both superconductive films and gold conductive paths (right). Substrate dimensions are 2.54 x 2.54 cm.

Next, a measurement circuit was designed to perform d.c. four-probe resistance measurements on the superconductive films. The measurement circuit was fabricated on a 2.54- x 1.27- x 0.10-cm alumina substrate using conventional multilayer thick-film processing. Each circuit contained three surface-mounted electronic components, namely two 8x2 multiplexers and one amplifier. One of the multiplexers was used to direct applied current from an external current source to the outer two contacts of each superconductive film under test, and the other multiplexer was used to direct the voltage signals generated across the inner two contacts to the external data storage system. Prior to leaving the hybrid circuit, the generated voltages were amplified by a factor of ten using the on-board amplifier. Additionally, a Platinum Resistance Thermometer (PRT) temperature sensor was located near the active components to monitor the extent of self-heating of the electronics during operation.

The measurement circuit was prepared using eight printed layers, including two gold conductive layers, two gold via fills, three dielectric layers, and one solderable platinum-gold layer. The gold conductive layers provided the necessary conductive paths for directing current and

voltage signals to and from the superconductive films. The dielectric layers were used to separate the conductive layers with via fills appropriately connecting electrical paths, thus producing a multilayer circuit with a reduced surface area. Finally, platinum-gold was used to produce solderable connections for off-circuit wiring. Figure 2 shows the circuit after printing and firing of (a) the initial gold layer, (b) two dielectric layers, (c) the associated via fills, (d) the second conductive layer, (e) the platinum-gold layer, and (f) the final dielectric layer.

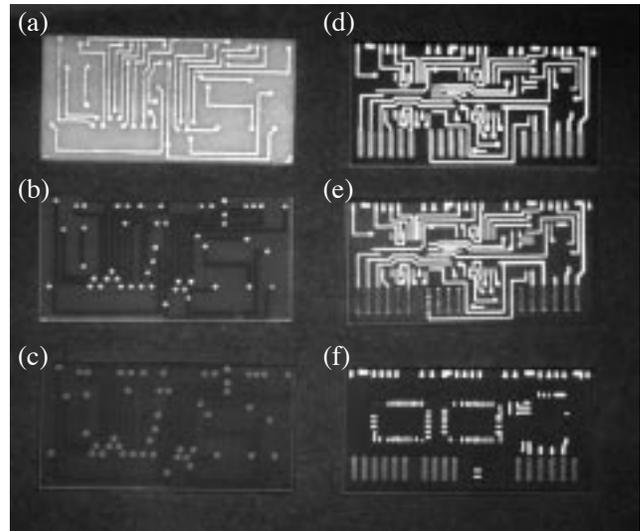


Figure 2. Measurement circuit after printing and firing of (a) the initial gold layer, (b) two dielectric layers, (c) the associated via fills, (d) the second conductive layer, (e) the platinum-gold layer, and (f) the final dielectric layer. Each substrate has dimensions of 2.54 x 1.27 cm.

The surface-mounted components were attached to the measurement circuit, wire bonded, and glob-topped. Figure 3 shows a typical circuit after integration of the electronic components. Three additional PRT temperature sensors were then integrated in the same manner near the superconductive film specimens on the YSZ substrate to permit localized temperature measurement of the films during operation. To complete the hybrid circuit, the alumina substrate was adhesively bonded to the YSZ substrate, and the gold conductive paths to the superconductive films were electrically connected with wire bonds. For these connections, redundant wire bonds were used to ensure reliability. Figure 4 shows a typical, fully-integrated superconductive circuit. A magnified image showing the gold wire bonds connecting the conductive paths from the YSZ and alumina substrates is provided in Figure 5.

Circuit Operation

During operation of the hybrid circuit, the resistance of each superconductive film was measured at temperatures

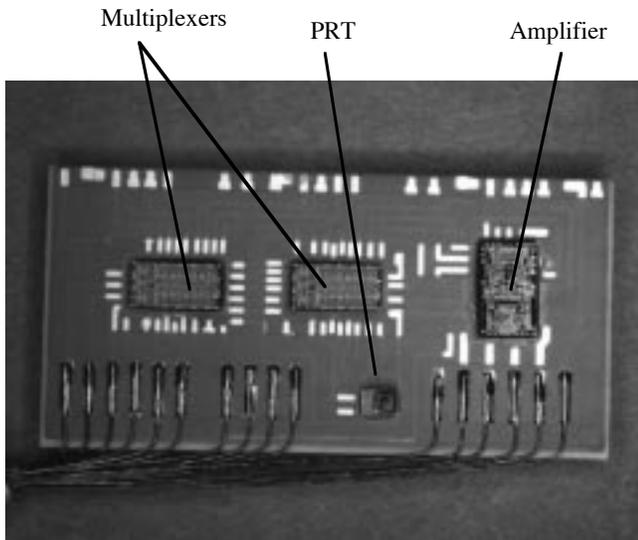


Figure 3. Typical measurement circuit after attachment of electronic components and off-circuit wiring, before wire bonding and glob-topping of the electronic components.

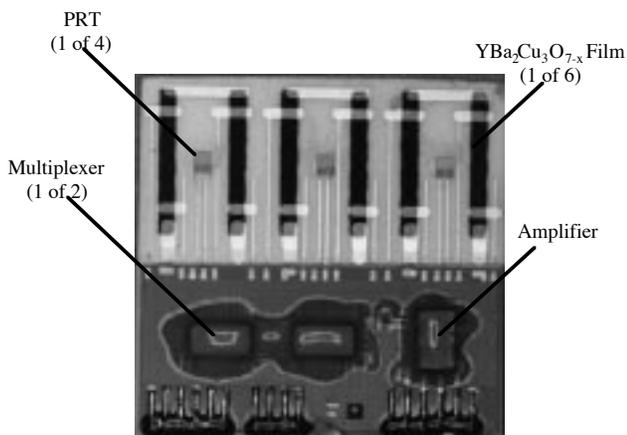


Figure 4. Fully-integrated hybrid circuit containing six superconductive thick films. Dimensions are 2.54 x 2.54 cm.

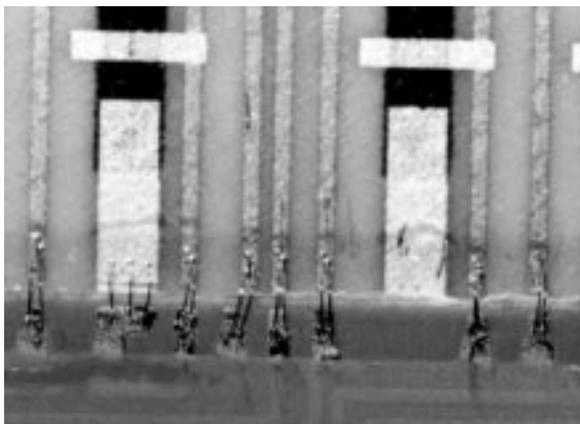


Figure 5. Magnified image of the redundant gold wire bonds connecting the alumina and YSZ substrates.

ranging from 75 to 250K using an applied current of 0.1 mA. From these data, the temperature at which the films

became superconductive, or the critical transition temperature, T_c , was determined. Additionally, the critical current density, J_c , of each specimen was determined at periodic intervals at a constant temperature of 75K. The J_c was measured by applying currents from 0 to 15.9 mA to each superconductive film using a current increment of 0.1 mA. For both measurements, the films were considered superconductive when the voltage generated across the inner two electrical contacts was less than 0.01 mV.

Integration and Testing

Four measurement circuits were selected for spaceflight including circuits containing both thin- and thick-film superconductive specimens. Two circuits contained $YBa_2Cu_3O_{7-x}$ thick films produced by NASA Langley Research Center (LaRC) in the manner previously described. One circuit contained specimens supplied by the Moscow Institute of Electronic Equipment (MIEE), including three $YBa_2Cu_3O_{7-x}$ thin films and three $Bi_2Sr_2Ca_2Cu_3O_x$ thin films produced by sputter deposition. The final circuit contained six $YBa_2Cu_3O_{7-x}$ thin films supplied by Eaton Corporation in cooperation with Los Alamos National Laboratory (LANL). The Eaton/LANL films were deposited using an ion-beam-assisted deposition (IBAD) technique.

The four circuits were bonded to the primary surfaces of a hollow copper cube and mounted inside a vacuum chamber for integration into the MIDAS experiment. A cryocooler was used to control the circuit temperature, and the cold finger extended into the vacuum chamber. To avoid damaging the cryocooler cold finger during high vibration events such as launch, the cube was mounted on a titanium structural support and thermally connected to the cryocooler cold finger via a copper strap. Figure 6 shows a schematic of the cube and support structure used to integrate the hybrid circuits into the MIDAS hardware. The vacuum chamber was evacuated prior to spaceflight, and an ion pump was used to maintain the necessary vacuum level for optimum cryocooler performance. To reduce water vapor and other contaminants and to promote a low vacuum pressure, the entire system was heated at temperatures up to 75°C for 72 hours while evacuating the chamber.

Once the vacuum chamber was evacuated, a series of vibration, thermal, and electrical tests were performed to qualify the MIDAS hardware for spaceflight. Vibration tests were performed to ensure that the loads experienced during launch would not damage either the circuits or the system hardware. Thermal tests were performed to verify that variations in the ambient spacecraft temperature would not affect the ability of the hardware to appropriately control the circuit temperature. Finally, electrical tests were conducted to demonstrate that the cooling capacity of the cryocooler was not compromised if the input voltage to

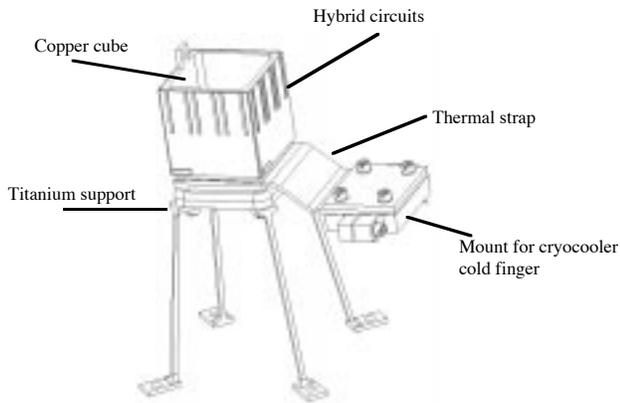


Figure 6. Schematic of the mounting configuration used to attach the flight circuits to the MIDAS hardware.

the experiment was varied. During each of these tests, the circuits containing the high-temperature superconductive films were cooled from room temperature to 75K, held at that temperature for at least 30 minutes, and warmed back to room temperature. The specimens were cooled at a rate of approximately 3.5K per minute.

Additionally, the MIDAS data acquisition software was evaluated prior to shipment of the experiment to Kennedy Space Center (KSC) by performing three full iterations of the experiment during a 72-hour period using an accelerated interval for acquiring J_c data. This test was used to verify that all data were properly recorded and stored. During the course of the pre-flight testing, ten thermal cycles from room temperature to 75K were performed on the integrated circuits prior to launch. During each cycle, both T_c and J_c data were acquired for each superconductive film, demonstrating the operation of the hybrid circuits.

RESULTS AND DISCUSSION

In this work, hybrid circuits containing conventional electronic components and high-temperature superconductive films were designed, fabricated, and tested. The devices were prepared by bonding together and electrically connecting two substrates, one containing the superconductive films and the other containing a multilayer measurement circuit. This method of producing the hybrid circuit allowed superconductive films from different sources to be integrated into the circuit design. As a result of using different superconductive compositions and processing techniques, different substrates were required. For the thick film superconductors, polycrystalline YSZ substrates were used for deposition, whereas, for the thin film materials, single crystal substrates were employed. Designing and fabricating the measurement circuit separately allowed integration of these substrates without requiring the entire

circuit to be fabricated on a single crystal.

Additionally, both the superconductive films and the measurement circuitry were separately evaluated prior to combining the substrates to produce the hybrid devices. The adhesive used to bond the substrates together could not be removed without substantial risk of damage to either the circuitry or the superconductive films. Hence, once the substrates were bonded together, they could not be separated. By separately verifying the functionality and cryogenic performance of both the superconductive films and the measurement circuits, the reliability of the final device was greatly improved.

Four hybrid circuits were selected for on-orbit testing as part of the MIDAS experiment. Two of these circuits contained thick film $YBa_2Cu_3O_{7-x}$ superconductive elements produced at NASA-Langley Research Center. The other two circuits contained thin film specimens which were produced by MIEE and Eaton/LANL and integrated with the measurement circuitry by NASA. Each circuit and specimen was assigned a unique designation. The NASA LaRC thick film circuits were referred to as circuits 1 and 3 (C1 and C3), the MIEE thin film circuits were C2, and the Eaton/LANL thin film circuits were C4. Each circuit possessed six superconductive films (S1-S6). Hence, the first specimen on circuit 1 was referred to as C1 S1.

The four circuits were attached to the faces of the hollow copper cube and inserted into the vacuum chamber of the MIDAS experiment for ground- and space-based evaluation of electrical performance. A photograph showing the integrated cube inside the vacuum chamber is provided in Figure 7. Figure 8 shows the relative location of the vacuum chamber within the MIDAS experiment. In the latter photograph, the top cover of the experiment has been removed.

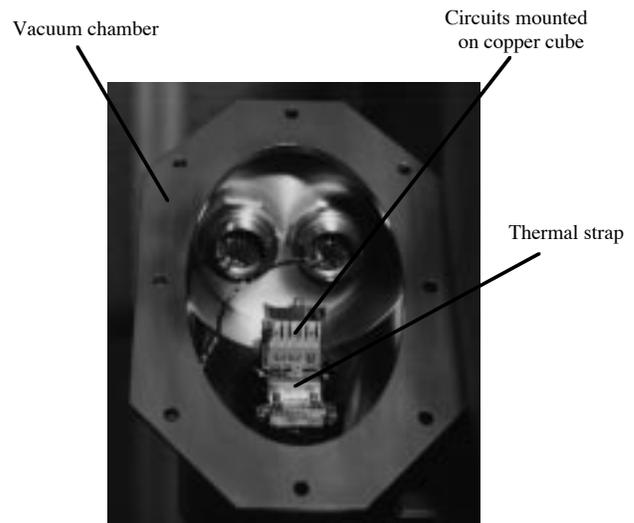


Figure 7. Photograph of the flight circuits mounted inside the MIDAS vacuum chamber.

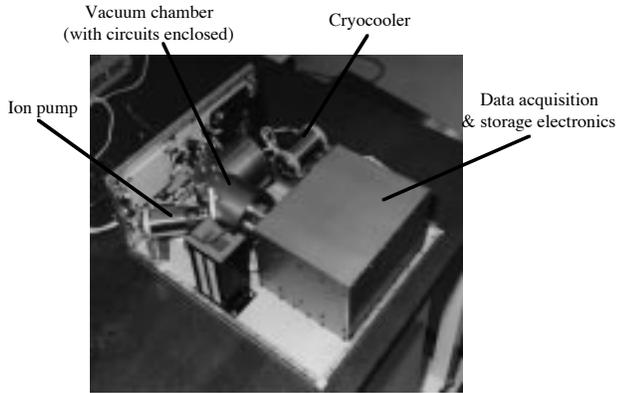


Figure 8. Photograph of the MIDAS flight hardware with the top cover removed.

The functionality of each circuit was verified before beginning pre-flight testing of the system. All circuits functioned as anticipated, with the exception of two superconductive thin films on Circuit 2. During application of the circuits onto the copper cube, a wire bond connecting one film pair to the electronic components was compromised. Because the films were addressed and measured in pairs, neither of the films was measurable during the remaining tests. However, no other wire bond failures were detected, and the remaining 22 superconductive films were successfully measured throughout all tests.

Throughout this investigation, each of the twelve $\text{YBa}_2\text{Cu}_3\text{O}_{7-x}$ thick films exhibited a critical transition temperature, T_c , of 87K and critical current density, J_c , values ranging from 1 to 25 A/cm^2 . Figures 9a and 9b show the typical T_c and J_c performance respectively for the six thick-film superconductors located on one of the hybrid circuits. These properties were commensurate with those obtained prior to combining the alumina and YSZ substrates to produce the measurement circuit devices. Additionally, these values remained constant during all pre-flight evaluations.

The circuits performed as designed during each of the pre-flight system tests, demonstrating no adverse effects or change in electrical performance for either the superconductive films or the measurement circuits. After insertion into the MIDAS vacuum chamber, the four circuits were heated, along with other components of the MIDAS hardware, to 75°C to reduce water vapor and other contaminants and to promote a low pressure within the chamber. The circuits were also subjected to repeated thermal cycles from room temperature to 75K, 3-axis vibrational loads to 16g, and near-continuous operation of the circuitry under vacuum and at cryogenic temperatures. The results of these tests indicate durability of the hybrid circuits, successful operation under the harsh conditions typically encountered in space systems, and reliable electrical performance during extended operational periods.

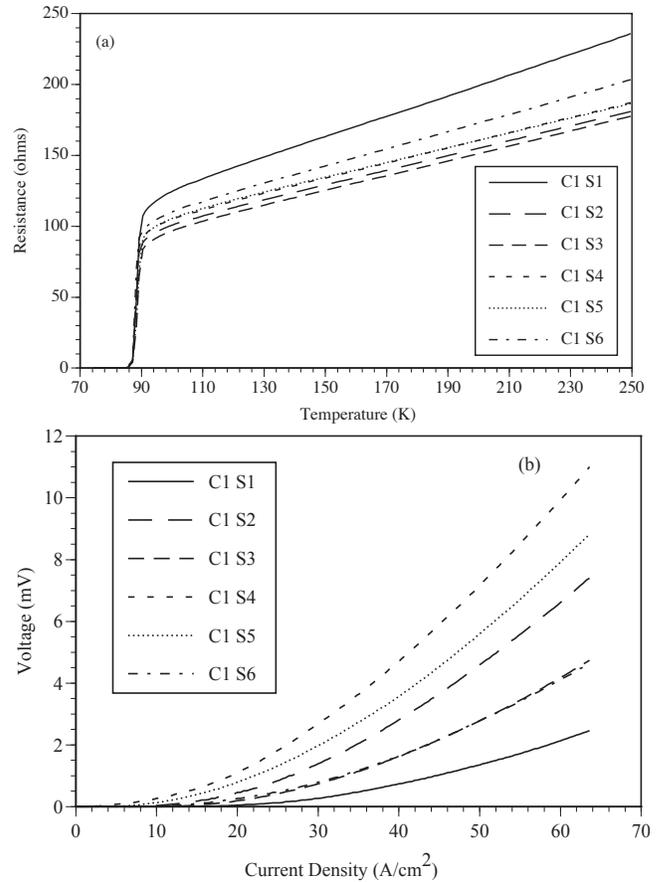


Figure 9. Pre-flight measurement of the T_c (a) and J_c (b) performance of the six superconductive thick films on C1.

CONCLUSIONS

In this work, thick and thin film high-temperature superconductors were integrated into a microelectronic circuit designed to perform d.c. four-probe resistance measurements from room temperature to 75K. To allow the incorporation of films from different sources, the integrated devices were assembled by bonding and electrically connecting a substrate containing six superconductive films to a prepared measurement circuit. In this manner, both thin and thick film materials produced by different processing techniques could be integrated and tested using the same measurement circuit design.

Four of the hybrid circuits containing high-temperature superconductive films were assembled and incorporated into the MIDAS experiment for on-orbit evaluation of the superconductive properties. Prior to flight, the performance of the circuits was evaluated on the ground under flight-like conditions. During these tests, the circuits were subjected to ten thermal cycles, evaluated before and after vibration loads, and operated for extended periods of time under vacuum at cryogenic temperatures. The results of these

tests indicate that durable superconductive devices can be successfully designed, fabricated, and integrated into complex hardware systems such as those required for spacecraft instruments.

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1. AGENCY USE ONLY (Leave blank)		2. REPORT DATE September 1998	3. REPORT TYPE AND DATES COVERED Technical Memorandum	
4. TITLE AND SUBTITLE Assembly and Integration of Superconductive Measurement Circuits for a Spaceflight Experiment			5. FUNDING NUMBERS WU 956-17-00-01	
6. AUTHOR(S) Stephanie A. Wise, Purnell Hopson, Jr., and Johnny C. Mau				
7. PERFORMING ORGANIZATION NAME(S) AND ADDRESS(ES) NASA Langley Research Center Hampton, VA 23681-2199			8. PERFORMING ORGANIZATION REPORT NUMBER L-17775	
9. SPONSORING/MONITORING AGENCY NAME(S) AND ADDRESS(ES) National Aeronautics and Space Administration Washington, DC 20546-0001			10. SPONSORING/MONITORING AGENCY REPORT NUMBER NASA/TM-1998-208717	
11. SUPPLEMENTARY NOTES				
12a. DISTRIBUTION/AVAILABILITY STATEMENT Unclassified-Unlimited Subject Category 76 Distribution: Standard Availability: NASA CASI (301) 621-0390			12b. DISTRIBUTION CODE	
13. ABSTRACT (Maximum 200 words) Hybrid microelectronics containing both conventional electronic components and high-temperature superconductive films have been designed, fabricated, and tested. The devices operate from room temperature to 75K and perform d.c. four-probe resistance measurements on six superconductive specimens resident on each circuit. Four of these hybrid circuits were incorporated into the Materials In Devices As Superconductors (MIDAS) spaceflight experiment and evaluated over a 90-day period on the Mir space station. Prior to launch, comprehensive testing of the flight circuits was performed to determine the effects of thermal cycling, vibration loads, and long-term operation on circuit performance. This report describes the fabrication and assembly procedures used to produce the hybrid circuits, the techniques used to integrate the circuits into the MIDAS hardware system, and the results of pre-flight evaluations which verified circuit functionality.				
14. SUBJECT TERMS Microelectronics, hybrids, spaceflight, superconductive circuitry, thick films, high-temperature superconductors			15. NUMBER OF PAGES 11	
			16. PRICE CODE A03	
17. SECURITY CLASSIFICATION OF REPORT Unclassified	18. SECURITY CLASSIFICATION OF THIS PAGE Unclassified	19. SECURITY CLASSIFICATION OF ABSTRACT Unclassified	20. LIMITATION OF ABSTRACT	